

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: ELECTROLYTIC PROCESSING APPARATUS AND SUBSTRATE PROCESSING APPARATUS

		ETREEBBING ATTAIGNEDS		
of which is described and claimed i	n:			
() the attached specification, or				
(X) the specification in application	Serial No.	, filed January 30, 2004, and wit	h amendments throug	∍h
, or	•			,
() the specification in International	Application No., filed, and as amended	on (if applicable).		
I hereby state that I have reviewed a any amendment(s) referred to above	nd understand the content of the above-i	dentified specification, including t	he claims, as amende	d by
eacknowledge my duty to disclose defined in Title 37, Code of Federal	to the Patent and Trademark Office all Regulations, §1.56.	information known to me to be m	aterial to patentabilit	y as
hereby claim priority benefits under or patent or inventor's certificate lis filing date before that of the applic	Title 35, United States Code, §119 (and ted below and have also identified below ation on which priority is claimed:	§172 if this application is for a Des vany application for patent or inve	ign) of any application entor's certificate hav	n(s) ′ing
COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED	

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2003-25159	January 31, 2003	YES
Japan	2003-384322	November 13, 2003	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from <u>WATANABE & HOTTA</u> as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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The above application may be more particularly identified as follows:

U.S. Application Serial No. 10/767,253 Filing Date January 30, 2004

Applicant Reference Number <u>GEB2160-US</u> Atty Docket No. <u>2004-0147A</u>

Title of Invention <u>ELECTROLYTIC PROCESSING APPARATUS AND SUBSTRATE PROCESSING APPARATUS</u>